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L Number	Hits	Search Text	DB	Time stamp
1	2291677	wafer or wafers or substrate or substrate or semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/08 09:39
2	15906	dicing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/08 09:39
3	7490	vacuum near3 (chuck or chucks)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/08 09:39
4	20097	((wafer or wafers or substrate or substrate or semiconductor) with dicing wiht (vacuum near3 (chuck or chucks)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/08 09:39
5	61	((wafer or wafers or substrate or substrate or semiconductor) with dicing with (vacuum near3 (chuck or chucks)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/08 10:06
6	20	"5809987"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/08 09:55
7	0	((wafer or wafers or substrate or substrate or semiconductor) with dicing with (vacuum near3 (chuck or chucks))) and farnsworth.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/08 10:06
8	5	((wafer or wafers or substrate or substrate or semiconductor) with dicing with (vacuum near3 (chuck or chucks))) and farnsworth.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/08 10:09
9	243643	blades	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/08 10:07
10	0	((wafer or wafers or substrate or substrate or semiconductor) with dicing with (vacuum near3 (chuck or chucks))) same blades	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/08 10:07
11	22	((wafer or wafers or substrate or substrate or semiconductor) with dicing with (vacuum near3 (chuck or chucks))) and blades	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/08 10:07
12	53	((wafer or wafers or substrate or substrate or semiconductor) with dicing) and farnsworth.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/08 10:13
13	402	((wafer or wafers or substrate or substrate or semiconductor) with dicing) and blades	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/08 10:14